# Surface Mount Schottky **Power Rectifier**

## **SMA Power Surface Mount Package**

This device employs the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

### Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Over-Voltage Protection
- Low Forward Voltage Drop
- Pb-Free Package is Available
- **Mechanical Characteristics:**
- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 70 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Cathode Lead Indicated by Either Notch in Plastic Body or Polarity Band
- Available in 12 mm Tape, 5000 Units per 13 inch Reel, Add "T3" Suffix to Part Number
- Device Meets MSL1 Requirements
- Machine Model, C (>400 V) • ESD Ratings: Human Body Model, 3B (>8000 V)

### MAXIMUM RATINGS

| Rating  | Symbol   | Value       | Unit |
|---|--|-------------|------|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage                          | V <sub>RRM</sub><br>V <sub>RWM</sub><br>V <sub>R</sub> | 30          | V    |
| Average Rectified Forward Current<br>(At Rated V <sub>R</sub> , T <sub>C</sub> = 105°C)                         | Ι <sub>Ο</sub>   | 1.0         | A    |
| Peak Repetitive Forward Current<br>(At Rated V <sub>R</sub> , Square Wave, 100 kHz,<br>$T_{C} = 105^{\circ}C$ ) | I <sub>FRM</sub>                                       | 2.0         | A    |
| Non–Repetitive Peak Surge Current<br>(Surge Applied at Rated Load Conditions<br>Halfwave, Single Phase, 60 Hz)  | I <sub>FSM</sub>                                       | 25          | A    |
| Storage Temperature   | T <sub>stg</sub>                                       | -55 to +150 | °C   |
| Operating Junction Temperature  | TJ   | -55 to +125 | °C   |
| Voltage Rate of Change, (Rated V <sub>R</sub> , $T_J = 25^{\circ}C$ )   | dv/dt  | 10,000      | V/µs |

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



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### SCHOTTKY BARRIER RECTIFIER 1.0 AMPERES, 30 VOLTS



SMA CASE 403D PLASTIC

### MARKING DIAGRAM



| B1L3 | = Device Code       |
|------|---------------------|
| А    | = Assembly Location |
| L    | = Wafer Lot         |

= Wafer Lot

Υ = Year W = Work Week

### ORDERING INFORMATION

| Device      | Package          | Shipping <sup>†</sup> |
|-------------|------------------|-----------------------|
| MBRA130LT3  | SMA              | 5000/Tape & Reel      |
| MBRA130LT3G | SMA<br>(Pb–Free) | 5000/Tape & Reel      |

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

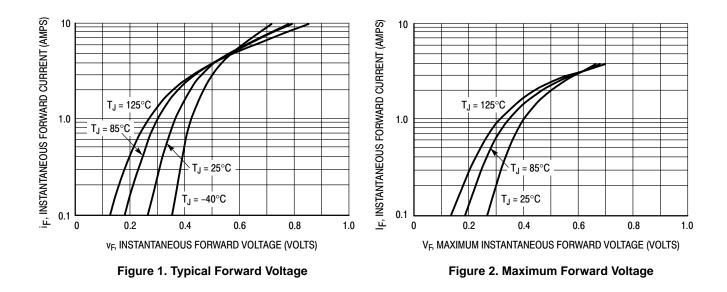
#### THERMAL CHARACTERISTICS

| Characteristic  | Symbol                        | Value    | Unit |
|---|-------------------------------|----------|------|
| Thermal Resistance — Junction-to-Lead (Note 1)<br>Thermal Resistance — Junction-to-Ambient (Note 1) | $R_{	heta JL}$ $R_{	heta JA}$ | 35<br>86 | °C/W |

#### **ELECTRICAL CHARACTERISTICS**

| Maximum Instantaneous Forward Voltage (Note 2) |  | V <sub>F</sub> | T <sub>J</sub> = 25°C | T <sub>J</sub> = 100°C | Volts |
|--|--|----------------|-----------------------|------------------------|-------|
| see Figure 2                                   | (I <sub>F</sub> = 1.0 A)<br>(I <sub>F</sub> = 2.0 A) |                | 0.41<br>0.47          | 0.35<br>0.43           |       |
| Maximum Instantaneous Reverse Current          |  | I <sub>R</sub> | T <sub>J</sub> = 25°C | T <sub>J</sub> = 100°C | mA    |
| see Figure 4                                   | (V <sub>R</sub> = 30 V)<br>(V <sub>R</sub> = 15 V)   |                | 1.0<br>0.4            | 25<br>12               |       |

1. Mounted on 2" Square PC Board with 1" Square Total Pad Size, PC Board FR4. 2. Pulse Test: Pulse Width  $\leq$  250 µs, Duty Cycle  $\leq$  2.0%.



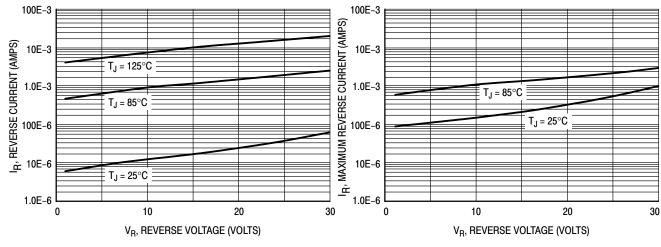


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

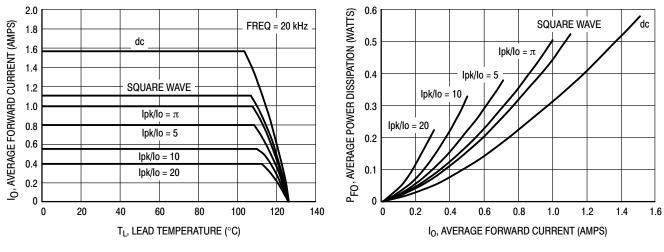
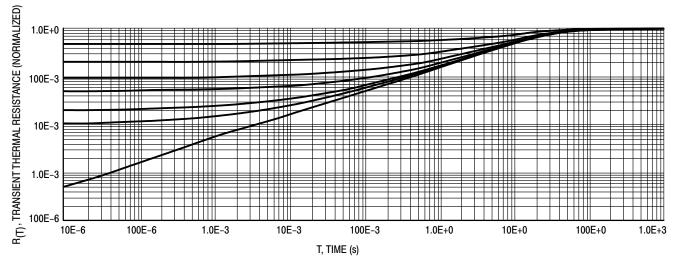




Figure 6. Forward Power Dissipation





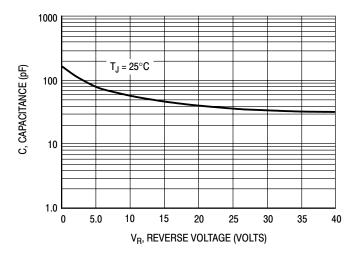
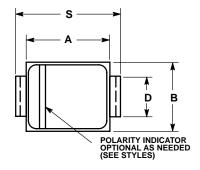


Figure 8. Capacitance

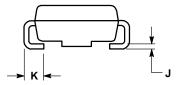
#### PACKAGE DIMENSIONS

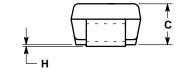
SMA CASE 403D-02 ISSUE B



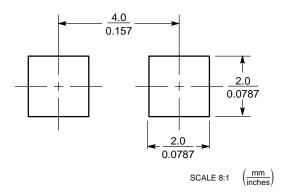
NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 403D–01 OBSOLETE, NEW STANDARD IS 403D–02

|     | INCHES |       | MILLIN | IETERS |
|-----|--------|-------|--------|--------|
| DIM | MIN    | MAX   | MIN    | MAX    |
| Α   | 0.160  | 0.180 | 4.06   | 4.57   |
| В   | 0.090  | 0.115 | 2.29   | 2.92   |
| c   | 0.075  | 0.095 | 1.91   | 2.41   |
| D   | 0.050  | 0.064 | 1.27   | 1.63   |
| Η   | 0.002  | 0.006 | 0.05   | 0.15   |
| J   | 0.006  | 0.016 | 0.15   | 0.41   |
| Κ   | 0.030  | 0.060 | 0.76   | 1.52   |
| S   | 0.190  | 0.220 | 4.83   | 5.59   |





**SOLDERING FOOTPRINT\*** 



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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